

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hwa-Sub OH	04/07/2010
Young-Hwan SHIN	04/07/2010
Jung-Woo CHO	04/02/2010
Sung-Jin LIM	04/07/2010

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	314, Maetan3-Dong, Yeongtong-Gu, Suwon,
City:	Gyeonggi-Do
State/Country:	REPUBLIC OF KOREA
Postal Code:	443-743

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12759083

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	075951-0194
NAME OF SUBMITTER:	Stephen A. Becker

Total Attachments: 3
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RECORDATION FORM COVER SHEET

Docket No.: 075951-0194

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)
Hwa-Sub OH, Young-Hwan SHIN, Jung-Woo CHO, Sung-Jin LIM

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**
 Internal Address:

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **April 7, 2010; April 7, 2010; April 2, 2010 and April 7, 2010 respectively**

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

Address: **314, Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-Do 443-743 KOREA**

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):
 A. Patent Application No(s).
 :

Additional numbers attached? Yes No

This document is being filed together with a new application.
 B. Patent No(s).

5. Name and address to whom correspondence concerning document should be mailed:

Name: **MCDERMOTT WILL & EMERY LLP**
 Internal Address:
 Street Address: **600 13th Street, N.W.**
 City: **Washington** State: **D. C.** Zip: **20005-3096**
 Phone Number: **202.756.8000**
 Fax Number: **202.756.8087**
 Email Address:

6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers _____
 Expiration Date _____

b. Deposit Account Number 500417
 Authorized User Name _____

9. Signature.
Stephen A. Becker 26,527  **April 13, 2010**

Name and Registration No. of Person Signing _____ Signature _____ Date _____

Total number of pages including cover sheet, attachments and documents: **3**

Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>Hwa-Sub OH</u>	(7) _____
(2) <u>Young-Hwan SHIN</u>	(8) _____
(3) <u>Jung-Woo CHO</u>	(9) _____
(4) <u>Sung-Jin LIM</u>	(10) _____
(5) _____	(11) _____
(6) _____	(12) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF MANUFACTURING PRINTED CIRCUIT BOARD

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

1)

Hwa Sub Oh
Name: Hwa-Sub OH

Apr. 07. 2010

2)

Young Hwan Shin
Name: Young-Hwan SHIN

Apr 07. 2010

3)

Jung Woo
Name: Jung-Woo CHO

04 / ~~02~~ / 2010

4)

Sung Jin Lim
Name: Sung-Jin LIM

Apr. 07. 2010